

REVISION		DCN	DATE	BY/APD
REV	DESCRIPTION			
1	Added 50 ohm requirement		4-13-11	KAK

NOTES UNLESS OTHERWISE SPECIFIED:

- ASSEMBLE IAW J-STD-001 CURRENT REVISION. THE ASSEMBLY IS TO MEET THE INSPECTION CRITERIA OF IPC-A-610, CLASS 2, CURRENT REVISION.
- REFERENCE DOCUMENTS:
SCHEMATIC DIAGRAM: 1075825SD.
BILL OF MATERIAL: 1075825-001
- THIS ASSEMBLY CONTAINS ELECTROSTATIC SENSITIVE DEVICES; HANDLE IAW MIL-STD-1686, CLASS 2.
- SOLDER PASTE THICKNESS TO BE .006 ±.002.
- CONVECTION HEATING ONLY IS TO BE USED DURING SOLDER REFLOW, NO IR.
- BAG AND TAG (OR MARK CONTAINER) WITH PART NO. 1075825-001 AND CURRENT REV LEVEL.
- VIAS ARE OMITTED FOR CLARITY.
- PADS OF SMALL CHIP RESISTORS AND CAPACITORS ARE OMITTED FOR CLARITY.
- AQUEOUS CLEANING IS REQUIRED.
- NO-LOAD PARTS: ALL COMPONENTS WITH TRIQUINT PART NO. 445930-001. SEE BOM.
- ASSEMBLY INSTRUCTIONS:
-STEP 1:
ASSEMBLE ALL SMD DEVICES.
-STEP 2:
INSTALL J1, J2, J3, AND J4.

TOP SIDE

